

## Phase Control Thyristor

### Types N3533Z#140 to N3533Z#220

Old Type No.: N1400CH02-20

#### Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V <sub>DRM</sub>	Repetitive peak off-state voltage, (note 1)	1400-2200	V
V <sub>DSM</sub>	Non-repetitive peak off-state voltage, (note 1)	1400-2200	V
V <sub>R<sub>RRM</sub></sub>	Repetitive peak reverse voltage, (note 1)	1400-2200	V
V <sub>R<sub>S</sub>M</sub>	Non-repetitive peak reverse voltage, (note 1)	1500-2300	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I <sub>T(AV)</sub>	Mean on-state current. T <sub>sink</sub> =55°C, (note 2)	3533	A
I <sub>T(AV)</sub>	Mean on-state current. T <sub>sink</sub> =85°C, (note 2)	2377	A
I <sub>T(AV)</sub>	Mean on-state current. T <sub>sink</sub> =85°C, (note 3)	1398	A
I <sub>T(RMS)</sub>	Nominal RMS on-state current. T <sub>sink</sub> =25°C, (note 2)	7052	A
I <sub>T(d.c.)</sub>	D.C. on-state current. T <sub>sink</sub> =25°C, (note 4)	5929	A
I <sub>TSM</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>rm</sub> =0.6V <sub>RRM</sub> , (note 5)	50	kA
I <sub>TSM2</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>rm</sub> ≤10V, (note 5)	60	kA
I <sup>2</sup> t	I <sup>2</sup> t capacity for fusing t <sub>p</sub> =10ms, V <sub>rm</sub> =0.6V <sub>RRM</sub> , (note 5)	12.5×10 <sup>6</sup>	A <sup>2</sup> s
I <sup>2</sup> t	I <sup>2</sup> t capacity for fusing t <sub>p</sub> =10ms, V <sub>rm</sub> ≤10V, (note 5)	18.0×10 <sup>6</sup>	A <sup>2</sup> s
di <sub>T</sub> /dt	Maximum rate of rise of on-state current (repetitive), (Note 6)	150	A/μs
	Maximum rate of rise of on-state current (non-repetitive), (Note 6)	300	A/μs
V <sub>RGM</sub>	Peak reverse gate voltage	5	V
P <sub>G(AV)</sub>	Mean forward gate power	5	W
P <sub>GM</sub>	Peak forward gate power	30	W
V <sub>GD</sub>	Non-trigger gate voltage, (Note 7)	0.25	V
T <sub>HS</sub>	Operating temperature range	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range	-40 to +150	°C

#### Notes: -

- 1) De-rating factor of 0.13% per °C is applicable for T<sub>j</sub> below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T<sub>j</sub> initial.
- 6) V<sub>D</sub>=67% V<sub>DRM</sub>, I<sub>TM</sub>=1000A, I<sub>FG</sub>=2A, t<sub>r</sub>≤0.5μs, T<sub>case</sub>=125°C.
- 7) Rated V<sub>DRM</sub>.

**Characteristics**

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNIT S
V <sub>TM</sub>	Maximum peak on-state voltage	-	-	1.25	I <sub>TM</sub> =3000A	V
V <sub>T0</sub>	Threshold voltage	-	-	0.97		V
r <sub>T</sub>	Slope resistance	-	-	0.095		mΩ
dv/dt	Critical rate of rise of off-state voltage	1000	-	-	V <sub>D</sub> =80% V <sub>DRM</sub> , linear ramp, Gate O/C	V/μs
I <sub>DRM</sub>	Peak off-state current	-	-	200	Rated V <sub>DRM</sub>	mA
I <sub>RRM</sub>	Peak reverse current	-	-	200	Rated V <sub>RRM</sub>	mA
V <sub>GT</sub>	Gate trigger voltage	-	-	3.0	T <sub>J</sub> =25°C, V <sub>D</sub> =10V, I <sub>T</sub> =3A	V
I <sub>GT</sub>	Gate trigger current	-	-	300		mA
I <sub>H</sub>	Holding current	-	-	1000	T <sub>J</sub> =25°C	mA
t <sub>gd</sub>	Gate controlled turn-on delay time	-	1.0	2.0	V <sub>D</sub> =67%V <sub>DRM</sub> , I <sub>TM</sub> =2000A, di/dt=10A/μs, I <sub>FG</sub> =2A, t <sub>r</sub> =0.5μs, T <sub>J</sub> =25°C	μs
t <sub>gt</sub>	Turn-on time	-	2.0	3.0		μs
Q <sub>rr</sub>	Recovered Charge	-	2700	-	I <sub>TM</sub> =4000A, t <sub>p</sub> =1000μs, di/dt=10A/μs, V <sub>r</sub> =50V	μC
Q <sub>ra</sub>	Recovered Charge, 50% chord	-	1700	2300		μC
I <sub>rm</sub>	Reverse recovery current	-	135	-		A
t <sub>rr</sub>	Reverse recovery time, 50% chord	-	25	-		μs
t <sub>q</sub>	Turn-off time	-	250	-	I <sub>TM</sub> =4000A, t <sub>p</sub> =1000μs, di/dt=10A/μs, V <sub>r</sub> =50V, V <sub>dr</sub> =80%V <sub>DRM</sub> , dV <sub>dr</sub> /dt=20V/μs	μs
		-	450	-	I <sub>TM</sub> =4000A, t <sub>p</sub> =1000μs, di/dt=10A/μs, V <sub>r</sub> =50V, V <sub>dr</sub> =80%V <sub>DRM</sub> , dV <sub>dr</sub> /dt=200V/μs	
R <sub>th(j-hs)</sub>	Thermal resistance, junction to heatsink	-	-	0.011	Double side cooled	K/W
		-	-	0.022	Single side cooled	K/W
F	Mounting force	27	-	47		kN
W <sub>t</sub>	Weight	-	1.7	-	Outline options ZC & ZT	kg
		-	1.2	-	Outline options ZD & ZV	

Notes: -

- 1) Unless otherwise indicated T<sub>J</sub>=125°C.
- 2) For other clamp forces please consult factory.

Notes on rupture rated packages.

This product is available with a non-rupture rated package.

For additional details on these products, please consult factory.

**Notes on Ratings and Characteristics**

**1.0 Voltage Grade Table**

Voltage Grade	$V_{DRM}$ $V_{DSM}$ $V_{RRM}$ V	$V_{RSM}$ V	$V_D$ $V_R$ DC V
14	1400	1500	930
16	1600	1700	1040
18	1800	1900	1150
20	2000	2100	1250
22	2200	2300	1350

**2.0 Extension of Voltage Grades**

This report is applicable to other and higher voltage grades when supply has been agreed by Sales/Production.

**3.0 De-rating Factor**

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T<sub>j</sub> below 25°C.

**4.0 Repetitive dv/dt**

Standard dv/dt is 1000V/μs.

**5.0 Rate of rise of on-state current**

The maximum un-primed rate of rise of on-state current must not exceed 300A/μs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/μs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

**6.0 Gate Drive**

The recommended pulse gate drive is 30V, 15Ω with a short-circuit current rise time of not more than 0.5μs. This gate drive must be applied when using the full di/dt capability of the device.

The pulse duration may need to be configured according to the application but should be no shorter than 20μs, otherwise an increase in pulse current may be needed to supply the necessary charge to trigger.

**7.0 Computer Modelling Parameters**

**7.1 Device Dissipation Calculations**

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^2 + 4 \cdot ff^2 \cdot r_T \cdot W_{AV}}}{2 \cdot ff^2 \cdot r_T}$$

and:

$$W_{AV} = \frac{\Delta T}{R_{th}}$$

$$\Delta T = T_{jmax} - T_K$$

Where V<sub>T0</sub>=0.97V, r<sub>T</sub>=0.095mΩ,

R<sub>th</sub> = Supplementary thermal impedance, see table below.

ff = Form factor, see table below.

Supplementary Thermal Impedance

Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.0124	0.0122	0.0121	0.0119	0.0117	0.0113	0.011
Square wave Single Side Cooled	0.0249	0.0248	0.0247	0.0246	0.0244	0.0241	0.022
Sine wave Double Side Cooled	0.0168	0.0140	0.0131	0.0118	0.0112		
Sine wave Single Side Cooled	0.0249	0.0247	0.0246	0.0244	0.0241		

Form Factors

Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.46	2.45	2	1.73	1.41	1.15	1
Sine wave	3.98	2.78	2.22	1.88	1.57		

### 7.2 Calculating $V_T$ using ABCD Coefficients

The on-state characteristic  $I_T$  vs.  $V_T$ , on page 5 is represented in two ways;

- (i) the well established  $V_{T0}$  and  $r_T$  tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for  $V_T$  in terms of  $I_T$  given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for  $V_T$  agree with the true device characteristic over a current range, which is limited to that plotted.

	25°C Coefficients	125°C Coefficients
A	1.172801	0.436704226
B	-0.03717729	0.06350879
C	$5.397833 \times 10^{-5}$	$1.720213 \times 10^{-4}$
D	$4.65 \times 10^{-3}$	$-3.856749 \times 10^{-3}$

### 7.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left( 1 - e^{-\frac{t}{\tau_p}} \right)$$

Where  $p = 1$  to  $n$ ,  $n$  is the number of terms in the series and:

- $t$  : Duration of heating pulse in seconds.
- $r_t$  : Thermal resistance at time  $t$ .
- $r_p$  : Amplitude of  $p_{th}$  term.
- $\tau_p$  : Time Constant of  $r_{th}$  term.

D.C. Double Side Cooled				
Term	1	2	3	4
$r_p$	$6.72 \times 10^{-3}$	$2.78 \times 10^{-3}$	$9.476 \times 10^{-4}$	$7.12 \times 10^{-4}$
$\tau_p$	1.0226	0.226	0.0586	$9.06 \times 10^{-3}$

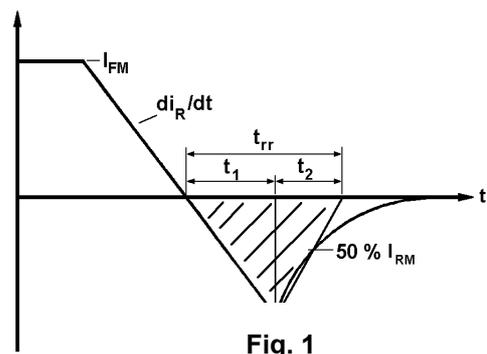
D.C. Single Side Cooled				
Term	1	2	3	4
$r_p$	0.01688	$4.42 \times 10^{-3}$	$1.79 \times 10^{-3}$	$8.72 \times 10^{-4}$
$\tau_p$	7.055	0.5206	0.1198	0.0128

### 8.0 Reverse recovery ratings

- (i)  $Q_{ra}$  is based on 50%  $I_{rm}$  chord as shown in Fig. 1.
- (ii)  $Q_{rr}$  is based on a 150 $\mu$ s integration time.

i.e. 
$$Q_{rr} = \int_0^{150\mu s} i_{rr} \cdot dt$$

(iii) 
$$K \text{ Factor} = \frac{t1}{t2}$$



**Curves**

Figure 1 - On-state characteristics of Limit device

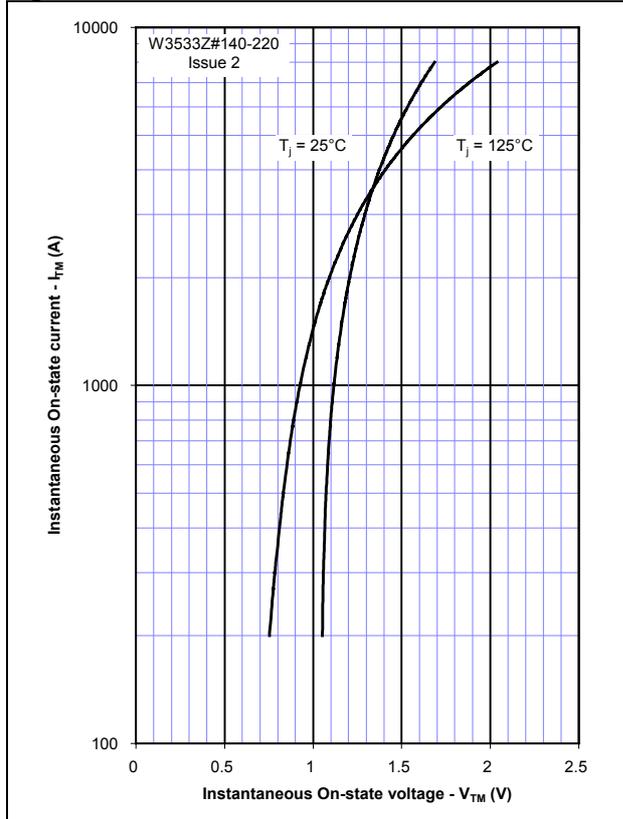


Figure 2 - Transient Thermal Impedance

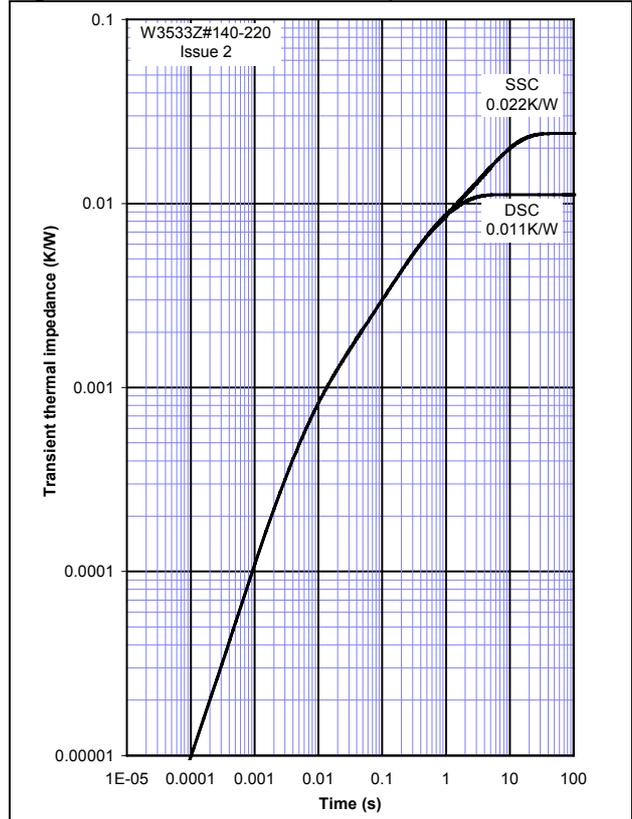


Figure 3 - Gate Characteristics - Trigger Limits

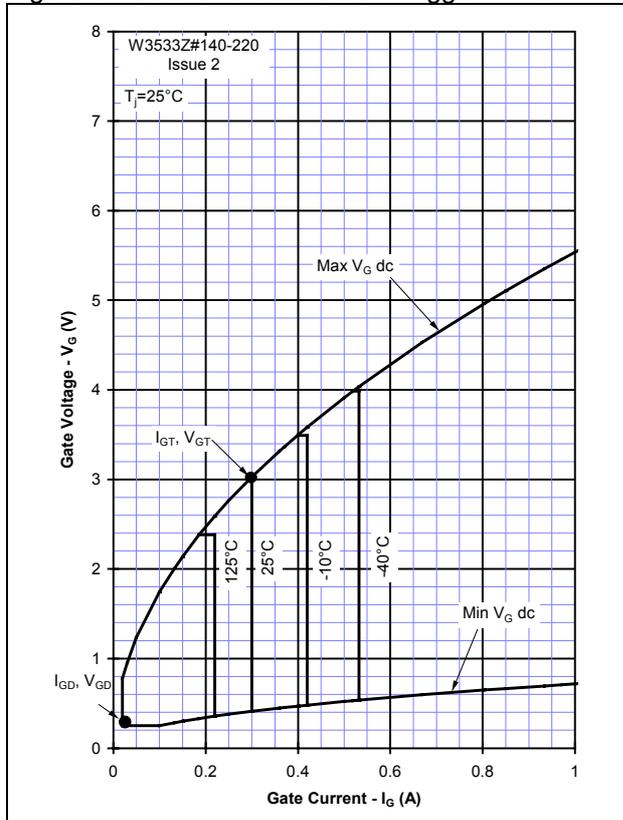


Figure 4 - Gate Characteristics - Power Curves

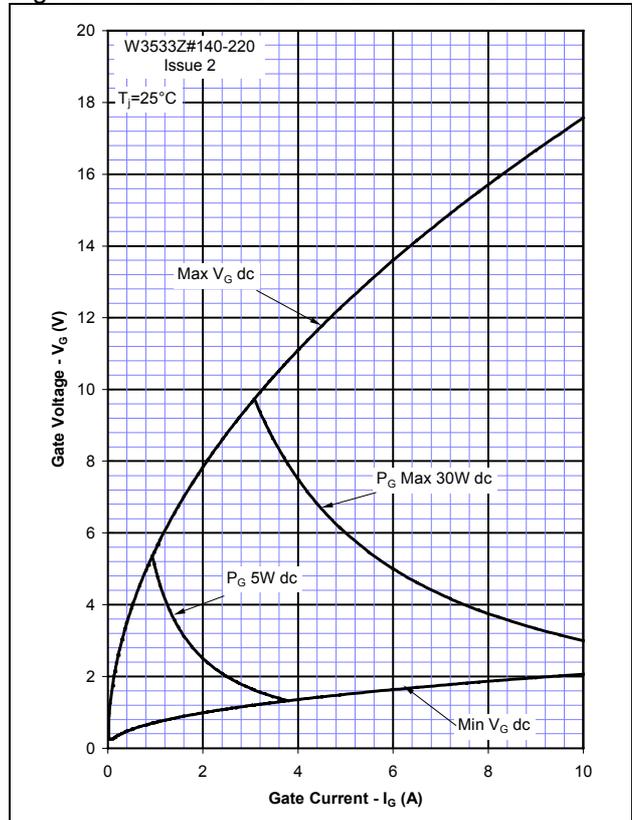


Figure 5 – Recovered Charge,  $Q_{rr}$

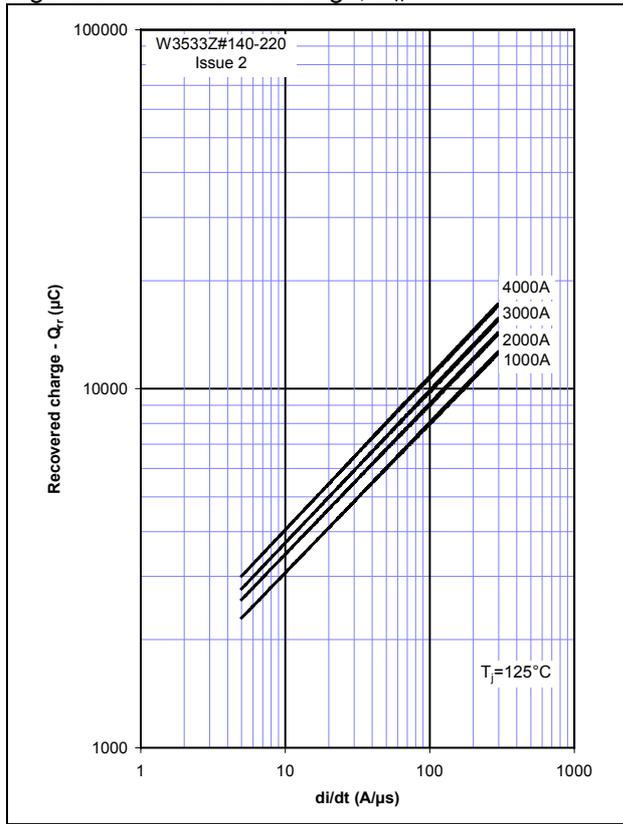


Figure 6 – Recovered charge,  $Q_{ra}$  (50% chord)

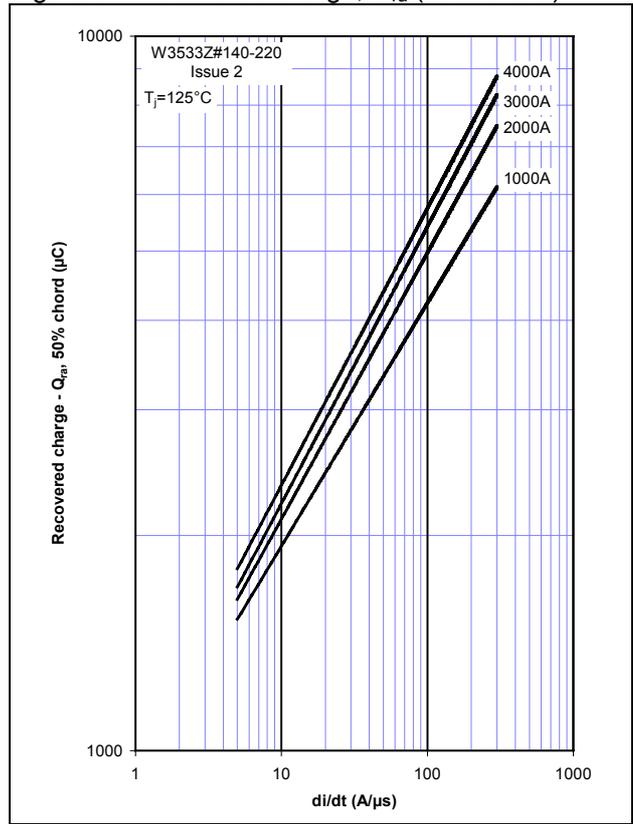


Figure 7 – Reverse recovery current,  $I_{rm}$

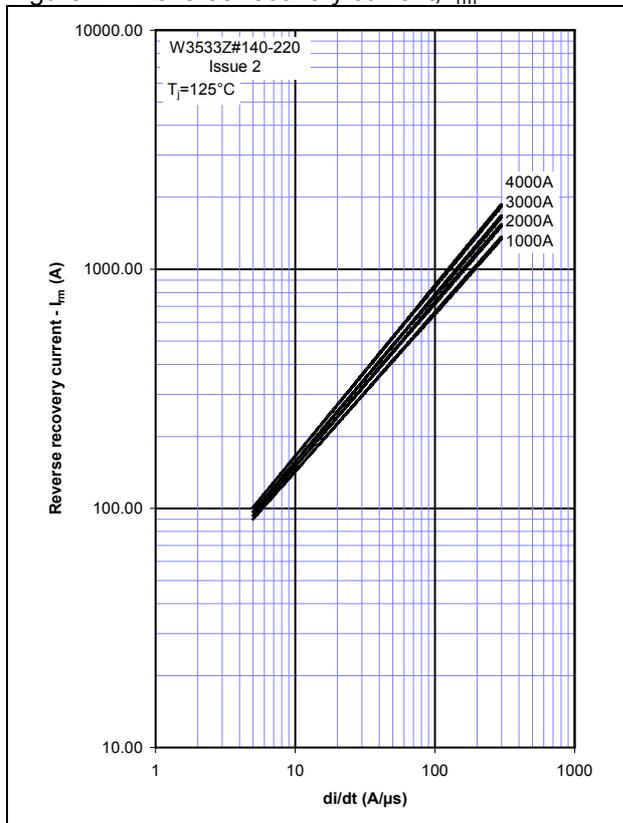


Figure 8 – Reverse recovery time,  $t_{rr}$  (50% chord)

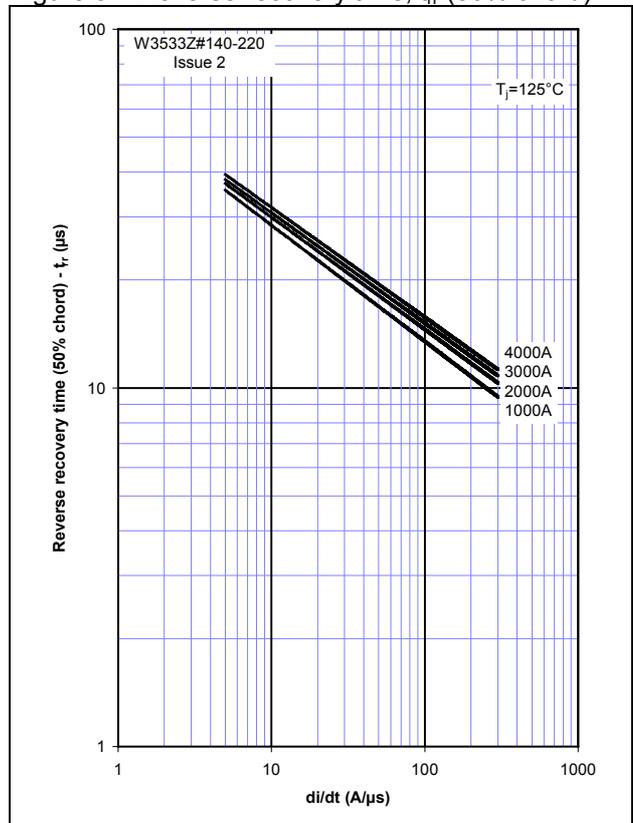


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

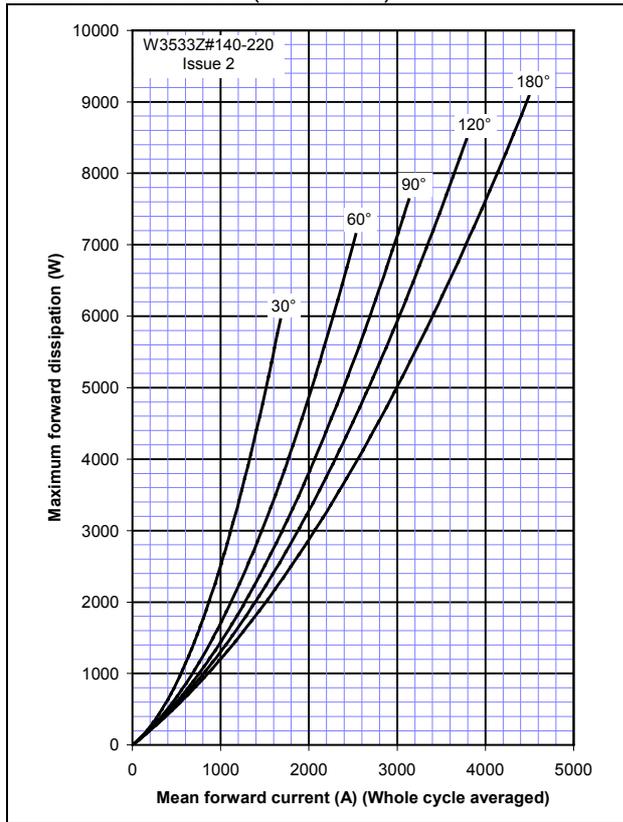


Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

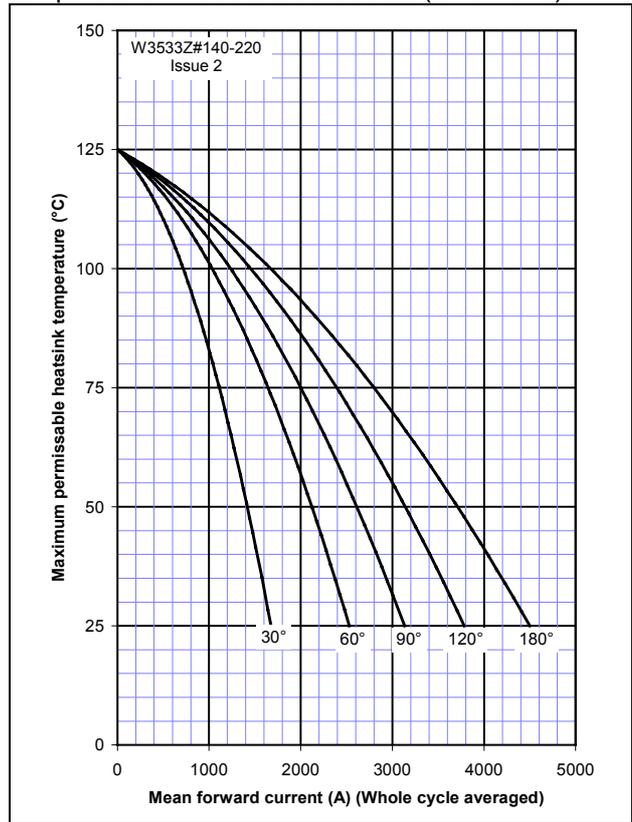


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

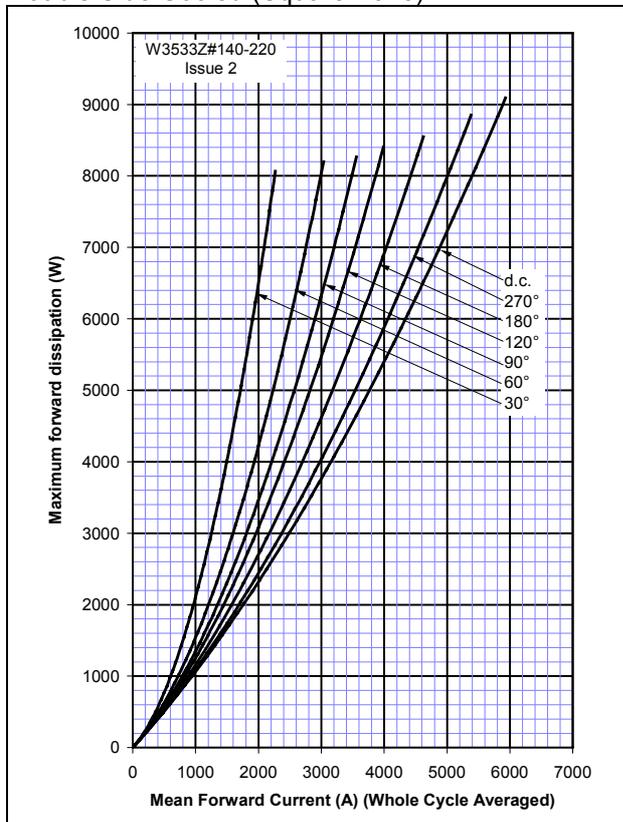


Figure 12 – On-state current vs. Heatsink temperature - Double Side Cooled (Square wave)

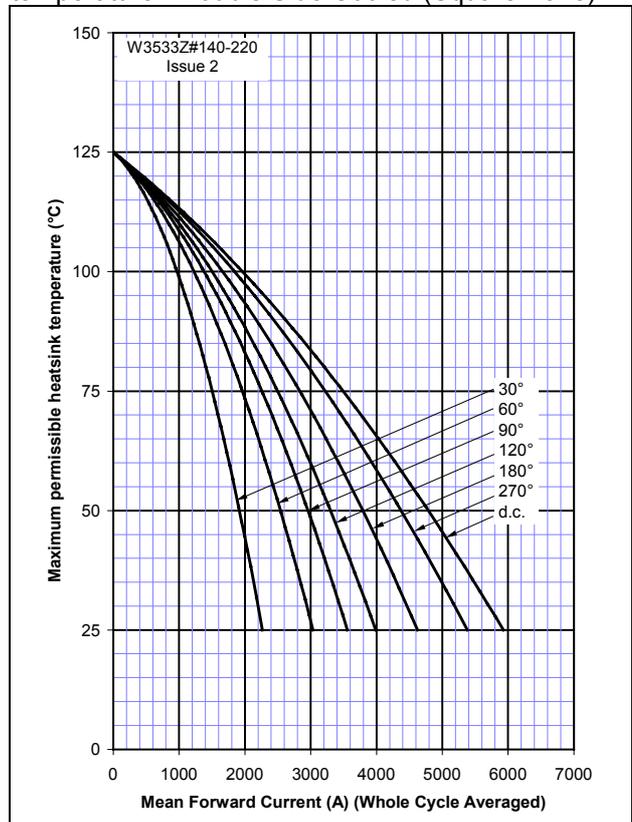


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

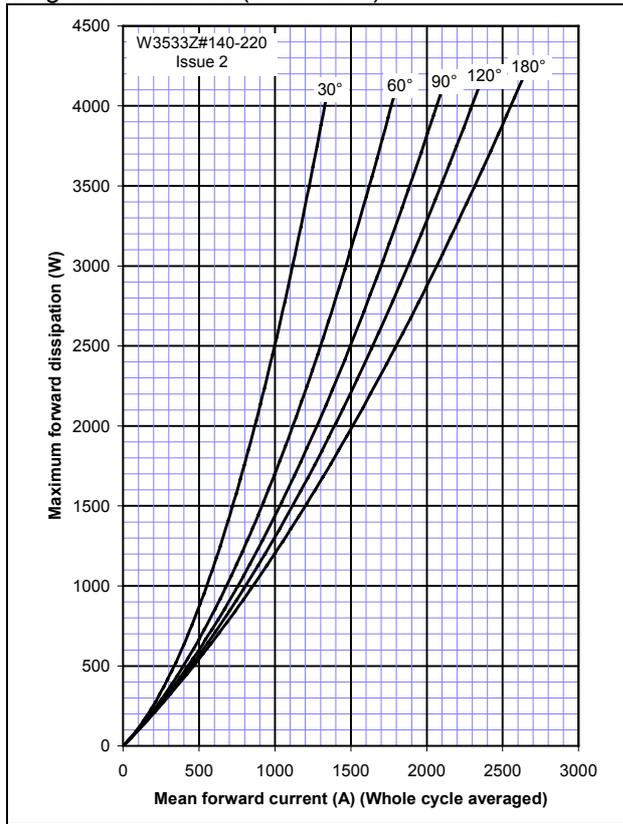


Figure 14 – On-state current vs. Heatsink temperature - Single Side Cooled (Sine wave)

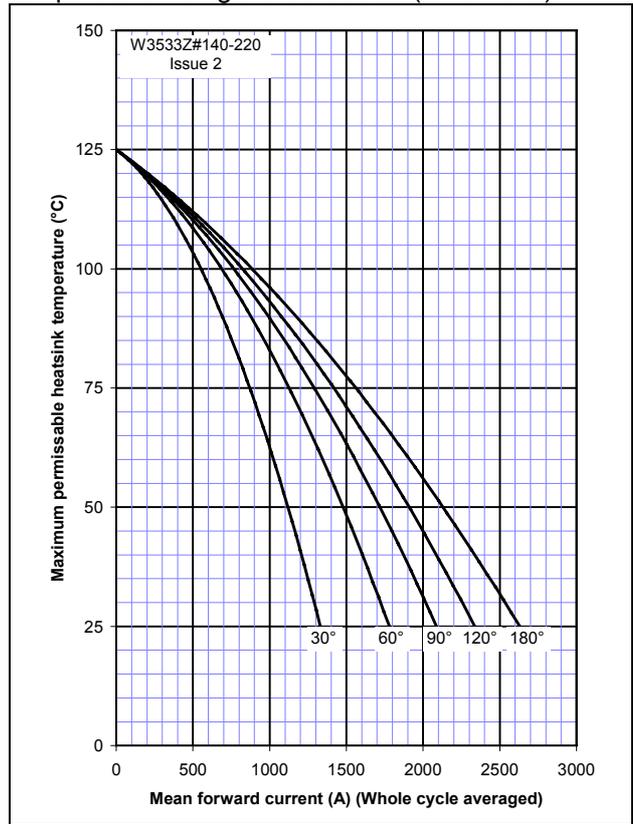


Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

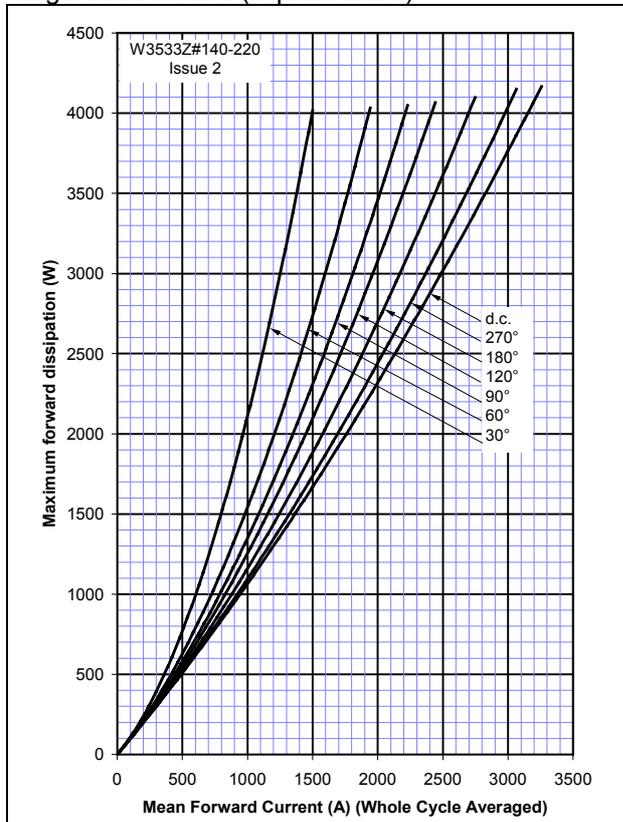


Figure 16 – On-state current vs. Heatsink temperature - Single Side Cooled (Square wave)

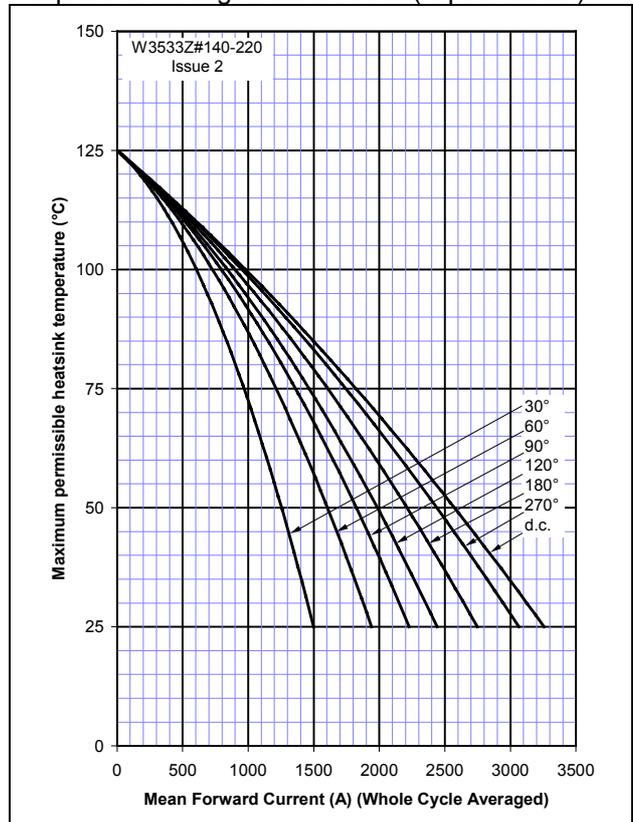
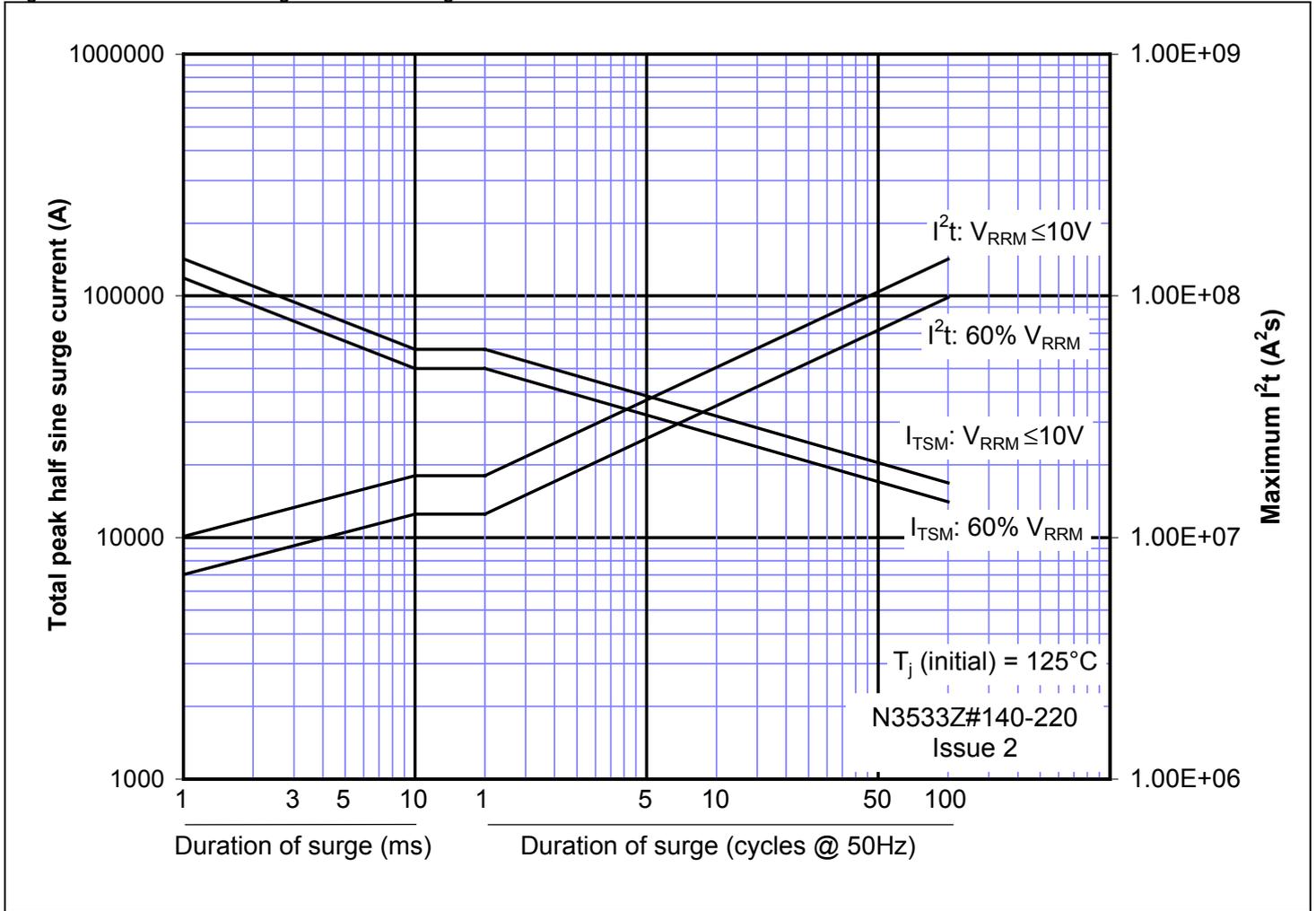
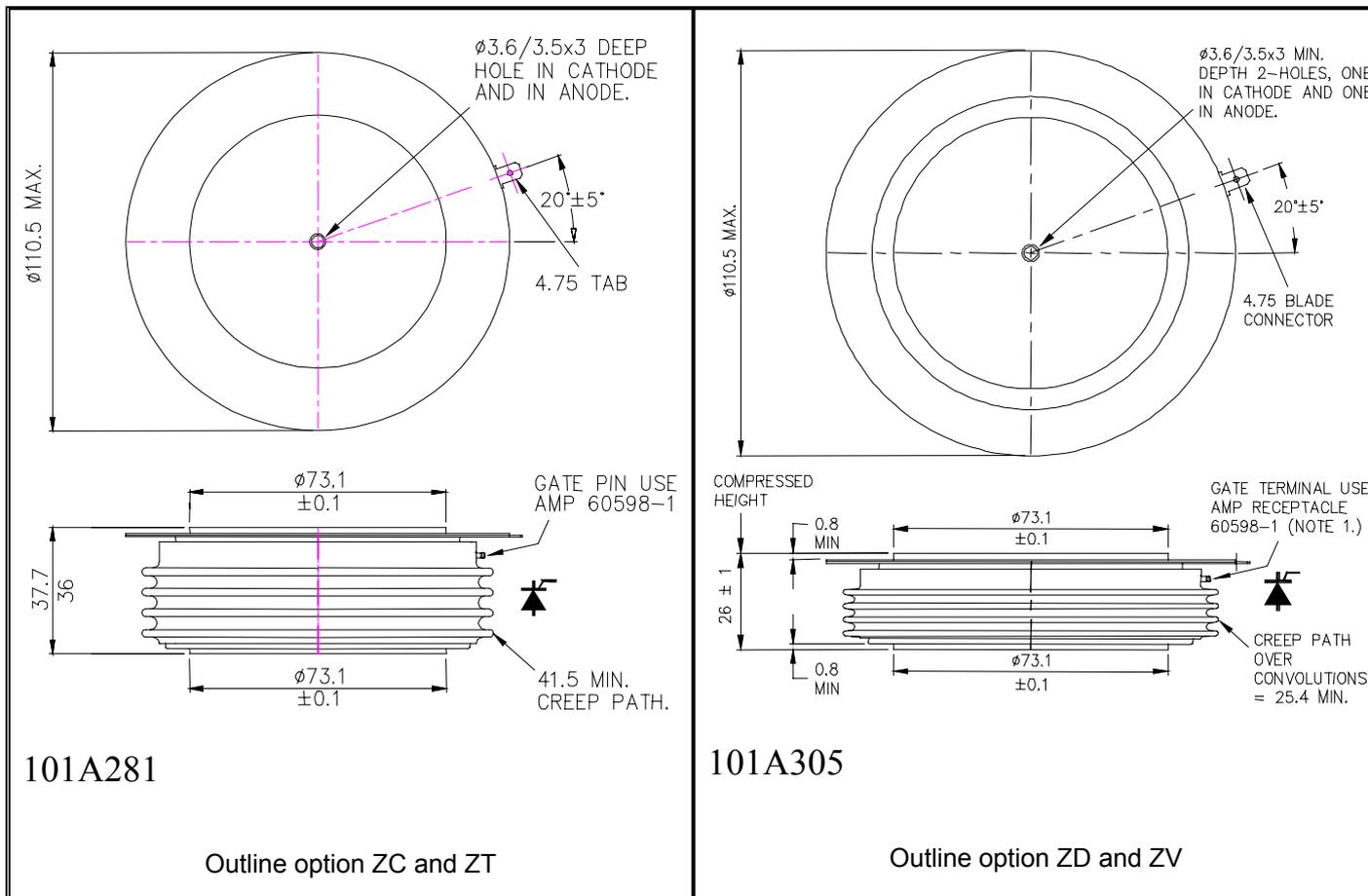


Figure 17 – Maximum surge and  $I^2t$  Ratings



**Outline Drawing & Ordering Information**



101A281

Outline option ZC and ZT

101A305

Outline option ZD and ZV

**ORDERING INFORMATION**

(Please quote 10 digit code as below)

<b>N3533</b>	<b>Z#</b>	<b>◆◆</b>	<b>0</b>
Fixed Type Code	Outline code ZC = 37.7mm clamp height, ZT = 37.7mm clamp height, rupture rated ZD = 26mm clamp height, ZV = 26mm clamp height, rupture rated	Voltage code V <sub>DRM</sub> /100 14-22	Fixed turn-off time code

Order code: N3533ZD220 – 2200V V<sub>RRM</sub>, 26mm clamp height capsule.

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